



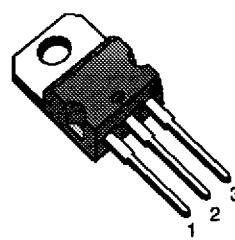
**SGS-THOMSON  
MICROELECTRONICS**

**STP13N10L  
STP13N10LFI**

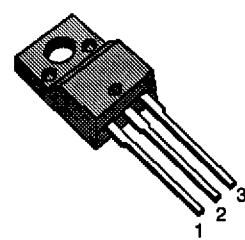
# N - CHANNEL ENHANCEMENT MODE LOW THRESHOLD POWER MOS TRANSISTOR

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STP13N10L	100 V	< 0.2 Ω	13 A
STP13N10LFI	100 V	< 0.2 Ω	9 A

- TYPICAL RDS(on) = 0.16 Ω
  - AVALANCHE RUGGEDNESS TECHNOLOGY
  - 100% AVALANCHE TESTED
  - REPETITIVE AVALANCHE DATA AT 100°C
  - LOW GATE CHARGE
  - HIGH CURRENT CAPABILITY
  - 175 °C OPERATING TEMPERATURE
  - LOGIC LEVEL COMPATIBLE INPUT
  - APPLICATION ORIENTED CHARACTERIZATION



TO-220

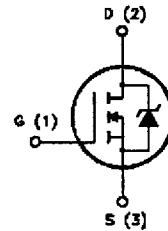


**ISOWATT220**

## APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
  - SOLENOID AND RELAY DRIVERS
  - REGULATORS
  - DC-DC & DC-AC CONVERTERS
  - MOTOR CONTROL, AUDIO AMPLIFIERS
  - AUTOMOTIVE ENVIRONMENT (INJECTION, ABS, AIR-BAG, LAMPDRIVERS, Etc.)

## **INTERNAL SCHEMATIC DIAGRAM**



## **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value		Unit
		STP13N10L	STP13N10LFI	
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	100	100	V
V <sub>DGR</sub>	Drain-gate Voltage (R <sub>GS</sub> = 20 kΩ)	100	100	V
V <sub>GS</sub>	Gate-source Voltage	± 15		V
I <sub>D</sub>	Drain Current (continuous) at T <sub>c</sub> = 25 °C	13	9	A
I <sub>D</sub>	Drain Current (continuous) at T <sub>c</sub> = 100 °C	9	6	A
I <sub>DM(•)</sub>	Drain Current (pulsed)	52	52	A
P <sub>tot</sub>	Total Dissipation at T <sub>c</sub> = 25 °C	80	35	W
	Derating Factor	0.53	0.23	W/°C
V <sub>ISO</sub>	Insulation Withstand Voltage (DC)	—	2000	V
T <sub>stg</sub>	Storage Temperature	-65 to 175		°C
T <sub>j</sub>	Max. Operating Junction Temperature	175		°C

- Pulse width limited by safe operating area

**THERMAL DATA**

			TO-220	ISOWATT220	
R <sub>thj-case</sub>	Thermal Resistance Junction-case	Max	1.87	4.3	°C/W
R <sub>thj-amb</sub>	Thermal Resistance Junction-ambient	Max	6.25		°C/W
R <sub>thc-sink</sub>	Thermal Resistance Case-sink	Typ	0.5		°C/W
T <sub>I</sub>	Maximum Lead Temperature For Soldering Purpose		300		°C

**AVALANCHE CHARACTERISTICS**

Symbol	Parameter	Max Value	Unit
I <sub>AR</sub>	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T <sub>j</sub> max, δ < 1%)	13	A
E <sub>AS</sub>	Single Pulse Avalanche Energy (starting T <sub>j</sub> = 25 °C, I <sub>d</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 25 V)	50	mJ
E <sub>AR</sub>	Repetitive Avalanche Energy (pulse width limited by T <sub>j</sub> max, δ < 1%)	10	mJ
I <sub>AR</sub>	Avalanche Current, Repetitive or Not-Repetitive (T <sub>c</sub> = 100 °C, pulse width limited by T <sub>j</sub> max, δ < 1%)	9	A

**ELECTRICAL CHARACTERISTICS (T<sub>case</sub> = 25 °C unless otherwise specified)****OFF**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	I <sub>D</sub> = 250 μA V <sub>GS</sub> = 0	100			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max Rating V <sub>DS</sub> = Max Rating × 0.8 T <sub>c</sub> = 125 °C			250 1000	μA μA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 15 V			± 100	nA

**ON (\*)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> I <sub>D</sub> = 1 mA	1	1.7	2.5	V
R <sub>D(S(on))</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 5 V I <sub>D</sub> = 6.5 A V <sub>GS</sub> = 5 V I <sub>D</sub> = 6.5 A T <sub>c</sub> = 100 °C		0.16	0.2 0.4	Ω Ω
I <sub>D(on)</sub>	On State Drain Current	V <sub>DS</sub> > I <sub>D(on)</sub> × R <sub>D(S(on))max</sub> V <sub>GS</sub> = 5 V	13			A

**DYNAMIC**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g <sub>fs</sub> (*)	Forward Transconductance	V <sub>DS</sub> > I <sub>D(on)</sub> × R <sub>D(S(on))max</sub> I <sub>D</sub> = 6.5 A	4	6		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V <sub>DS</sub> = 25 V f = 1 MHz V <sub>GS</sub> = 0		760 140 40	1000 200 60	pF pF pF

## ELECTRICAL CHARACTERISTICS (continued)

### SWITCHING RESISTIVE LOAD

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ $t_r$	Turn-on Time Rise Time	$V_{DD} = 50 \text{ V}$ $I_D = 6.5 \text{ A}$ $R_{GS} = 4.7 \Omega$ $V_{GS} = 5 \text{ V}$ (see test circuit, figure 3)		15 120	20 160	ns ns
$(di/dt)_{on}$	Turn-on Current Slope	$V_{DD} = 80 \text{ V}$ $I_D = 13 \text{ A}$ $R_{GS} = 4.7 \Omega$ $V_{GS} = 5 \text{ V}$ (see test circuit, figure 5)		200		A/ $\mu\text{s}$
$Q_g$ $Q_{gs}$ $Q_{gd}$	Total Gate Charge	$V_{DD} = 80 \text{ V}$ $I_D = 13 \text{ A}$ $V_{GS} = 5 \text{ V}$		20 6 8	30	nC

### SWITCHING INDUCTIVE LOAD

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{r(volt)}$ $t_r$ $t_c$	Off-voltage Rise Time Fall Time Cross-over Time	$V_{DD} = 80 \text{ V}$ $I_D = 13 \text{ A}$ $R_{GS} = 4.7 \Omega$ $V_{GS} = 5 \text{ V}$ (see test circuit, figure 5)		11 17 32	20 30 50	ns ns ns

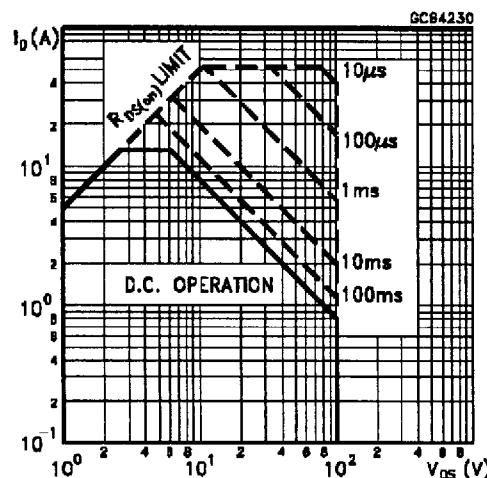
### SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_{SD}$ $I_{SDM(*)}$	Source-drain Current Source-drain Current (pulsed)				13 52	A A
$V_{SD} (*)$	Forward On Voltage	$I_{SD} = 13 \text{ A}$ $V_{GS} = 0$			1.5	V
$t_{rr}$ $Q_{rr}$ $I_{RRM}$	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 13 \text{ A}$ $di/dt = 100 \text{ A}/\mu\text{s}$ $V_R = 30 \text{ V}$ $T_j = 150^\circ\text{C}$ (see test circuit, figure 5)		110 0.4 8		ns $\mu\text{C}$ A

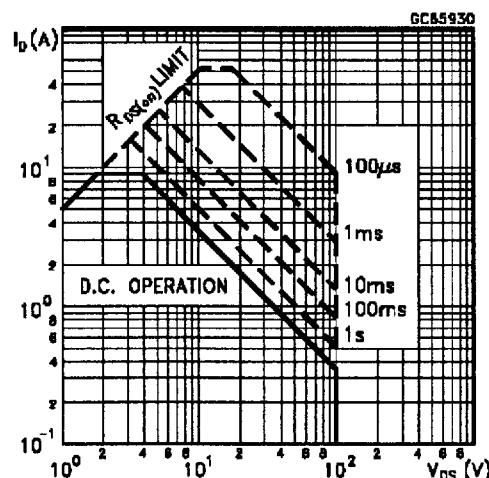
(\*) Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %

(\*) Pulse width limited by safe operating area

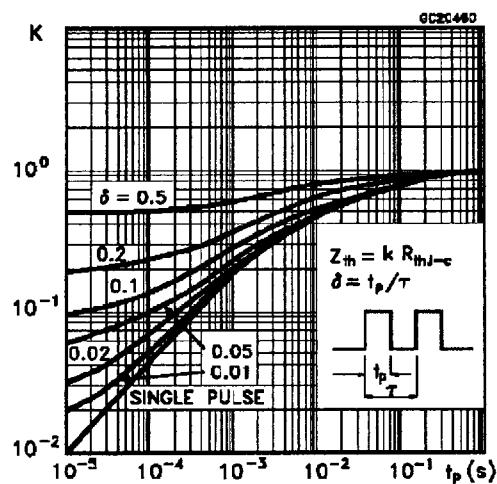
### Safe Operating Areas For TO-220



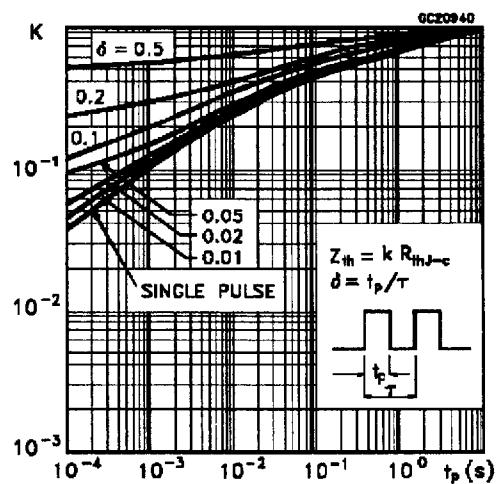
### Safe Operating Areas For ISOWATT220



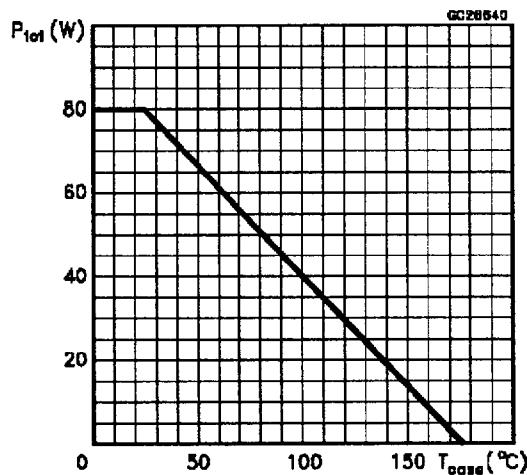
**Thermal Impedance For TO-220**



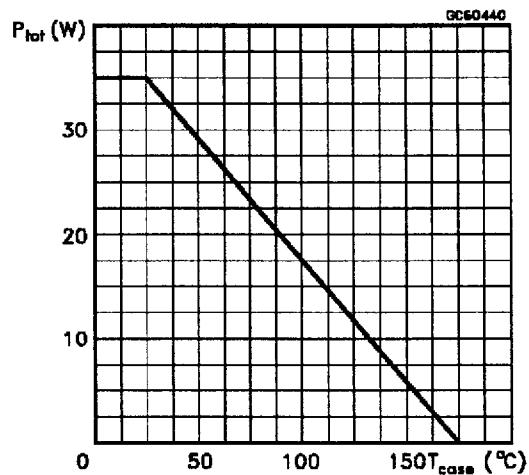
**Thermal Impedance For ISOWATT220**



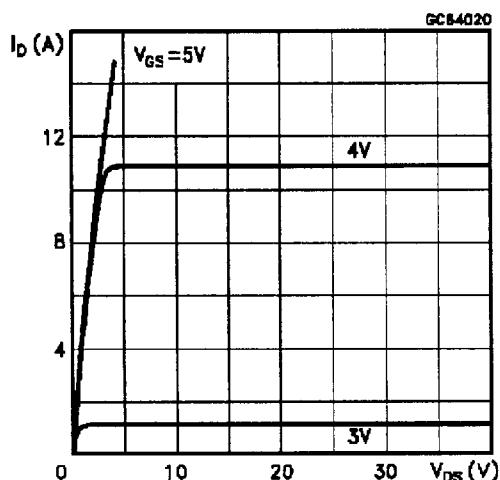
**Derating Curve For TO-220**



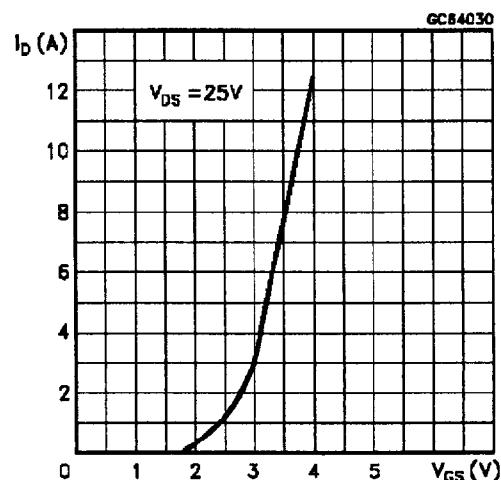
**Derating Curve For ISOWATT220**



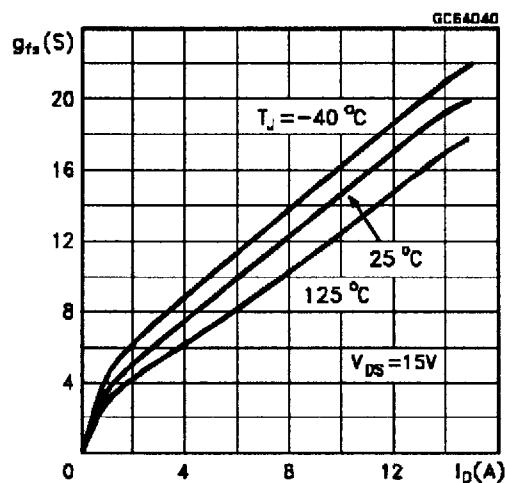
**Output Characteristics**



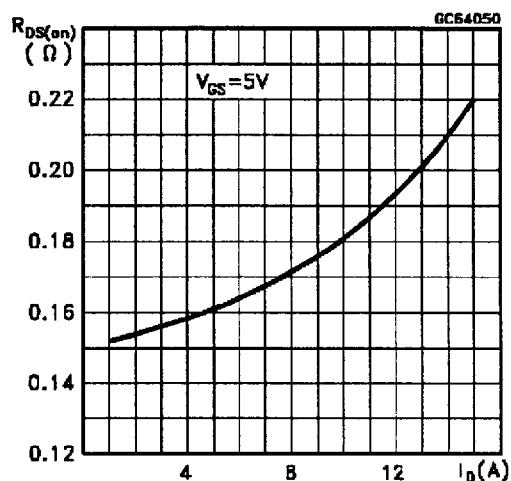
**Transfer Characteristics**



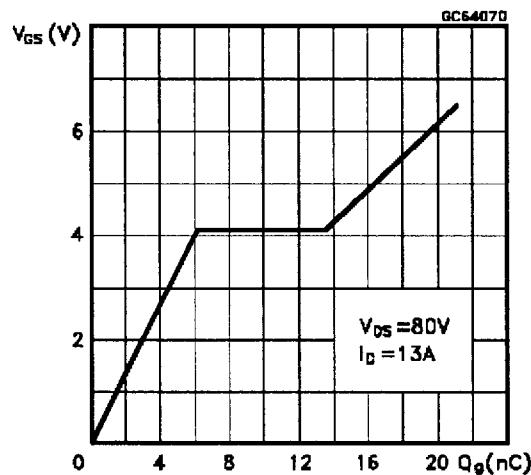
## Transconductance



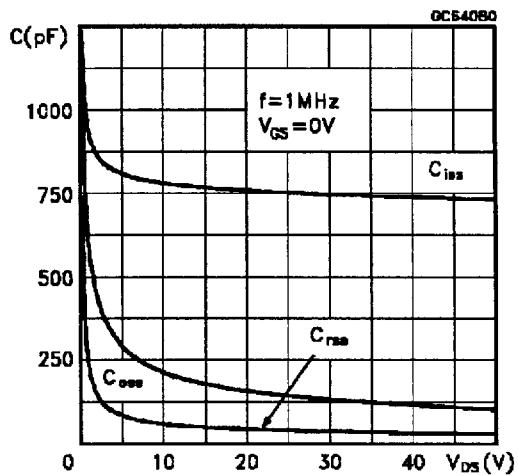
## Static Drain-source On Resistance



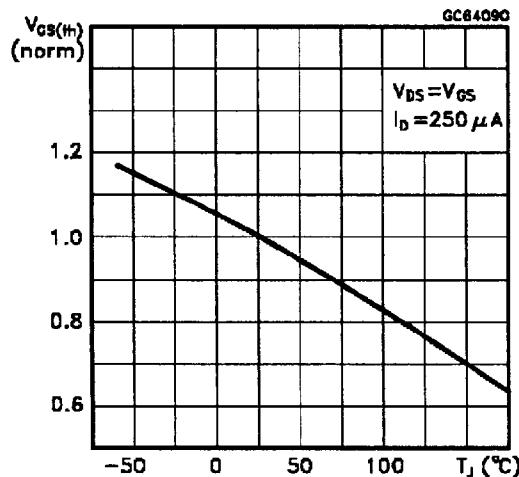
## Gate Charge vs Gate-source Voltage



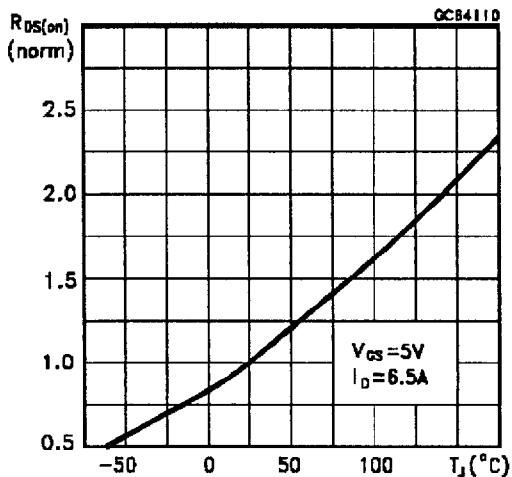
## Capacitance Variations



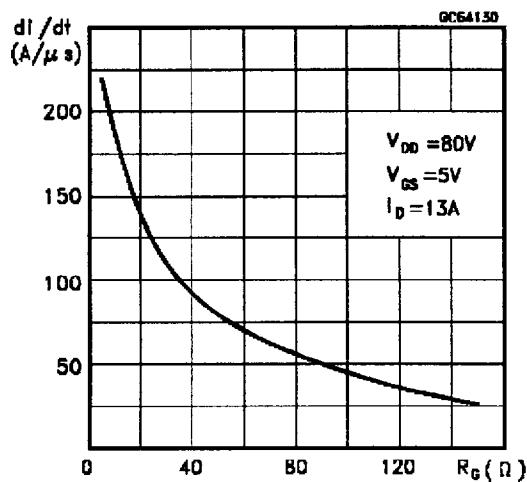
## Normalized Gate Threshold Voltage vs Temperature



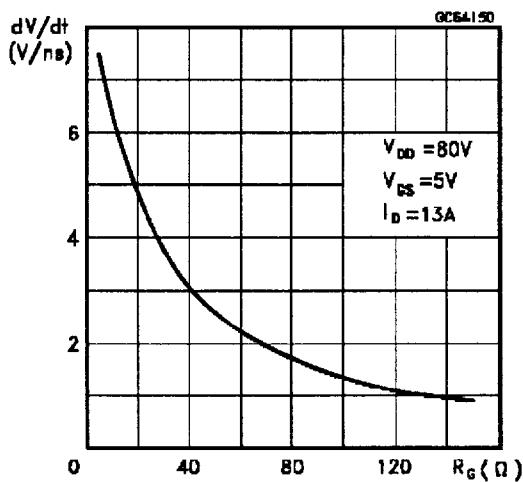
## Normalized On Resistance vs Temperature



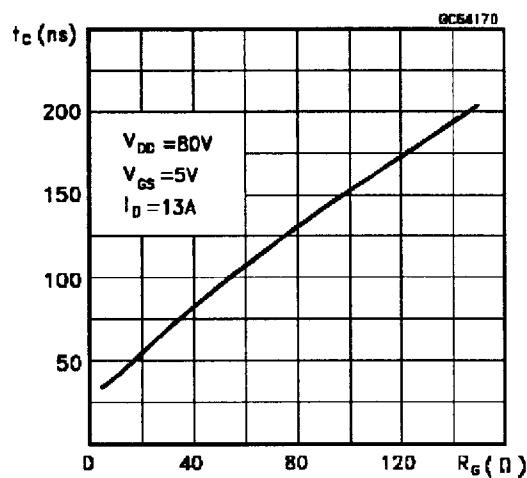
**Turn-on Current Slope**



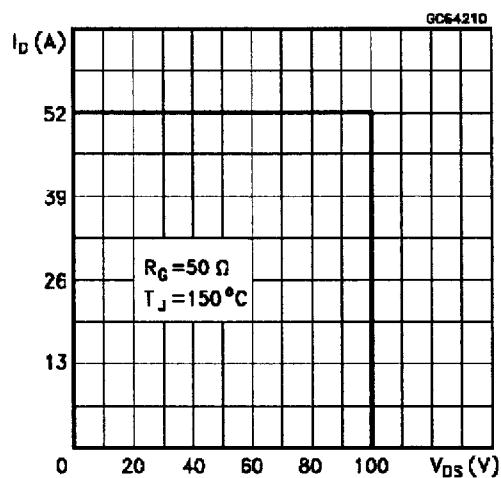
**Turn-off Drain-source Voltage Slope**



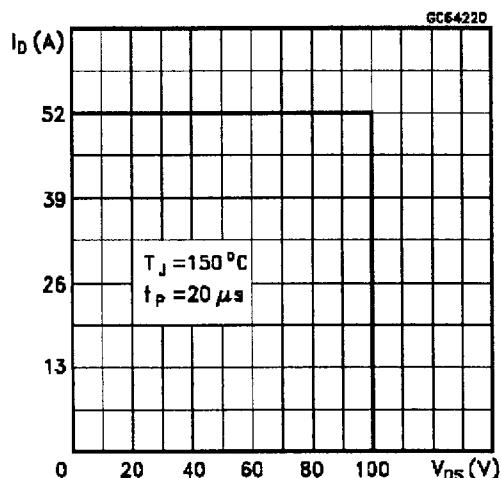
**Cross-over Time**



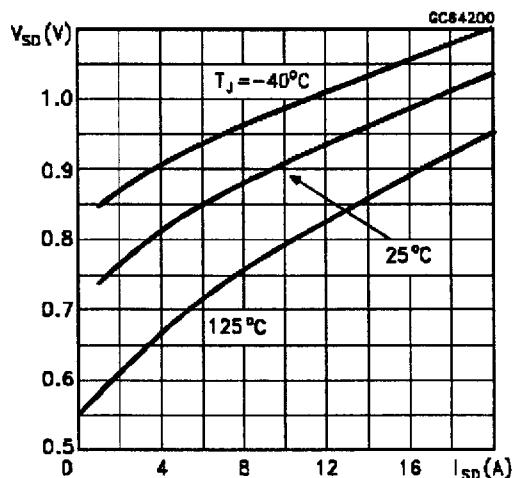
**Switching Safe Operating Area**

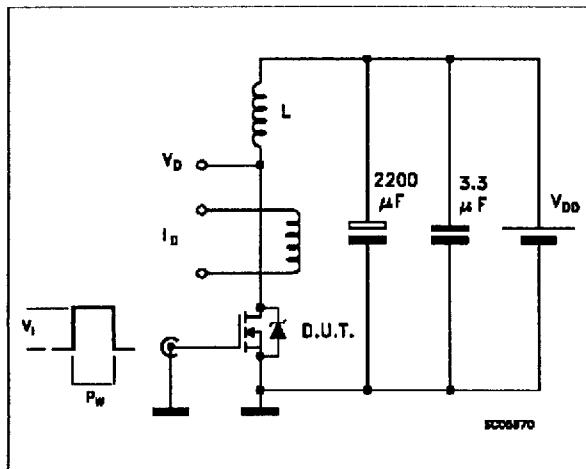
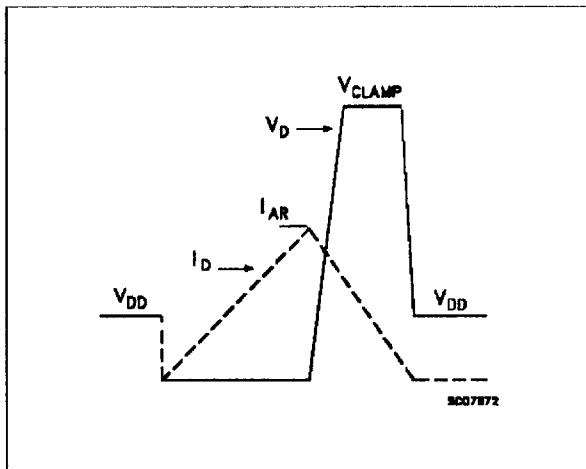
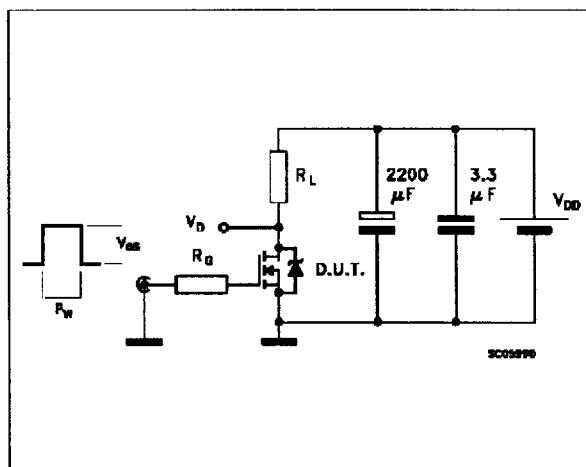
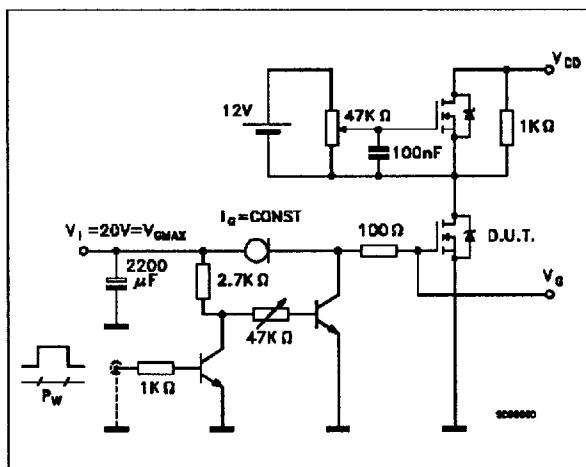
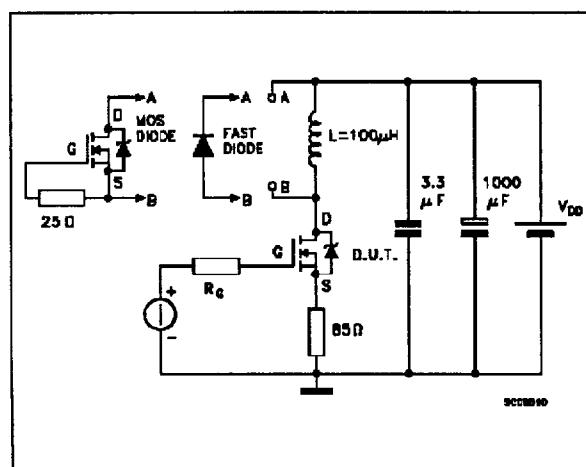


**Accidental Overload Area**



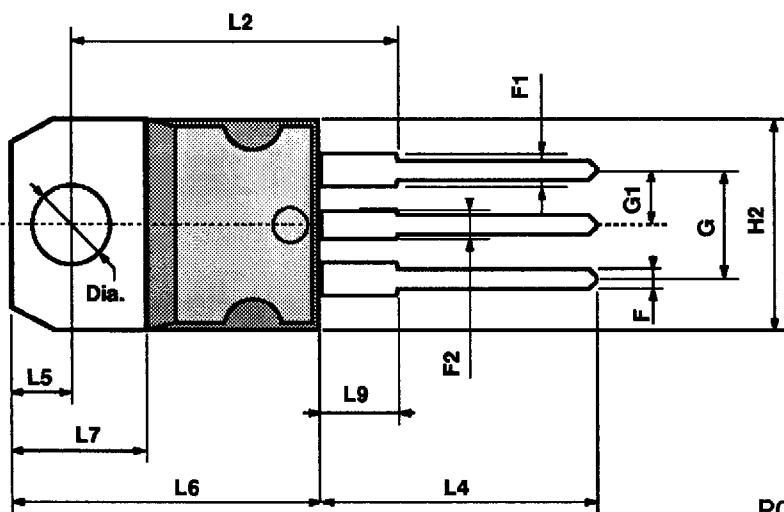
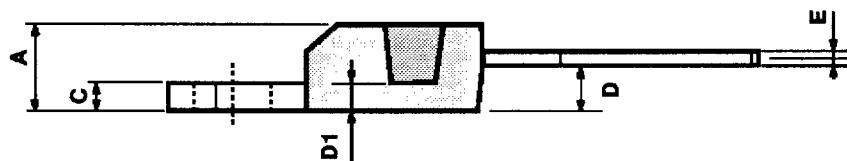
**Source-drain Diode Forward Characteristics**



**Fig. 1: Unclamped Inductive Load Test Circuits****Fig. 2: Unclamped Inductive Waveforms****Fig. 3: Switching Times Test Circuits For Resistive Load****Fig. 4: Gate Charge Test Circuit****Fig. 5: Test Circuit For Inductive Load Switching And Diode Reverse Recovery Time**

## TO-220 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
C	1.23		1.32	0.048		0.051
D	2.40		2.72	0.094		0.107
D1		1.27			0.050	
E	0.49		0.70	0.019		0.027
F	0.61		0.88	0.024		0.034
F1	1.14		1.70	0.044		0.067
F2	1.14		1.70	0.044		0.067
G	4.95		5.15	0.194		0.203
G1	2.4		2.7	0.094		0.106
H2	10.0		10.40	0.393		0.409
L2		16.4			0.645	
L4	13.0		14.0	0.511		0.551
L5	2.65		2.95	0.104		0.116
L6	15.25		15.75	0.600		0.620
L7	6.2		6.6	0.244		0.260
L9	3.5		3.93	0.137		0.154
DIA.	3.75		3.85	0.147		0.151



P011C

## ISOWATT220 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.4		0.7	0.015		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
H	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	0.385		0.417
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126

